

客户图

NOTES:

1.FINISH:

- HOUSING: LCP BLACK,UL94 V-0
- CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- CURRENT RATING: 3.0 AMP,AC/DC
- DIELECTRIC WITHSTANDING VOLTAGE: 500V,AC/Minute
- CONTACT RESISTANCE: 100mΩ MAX.
- INSULATION RESISTANCE: 1000 mΩ Min
- Operation Temperature:-40°C to125°C

3.SALT SPRAY TEST:

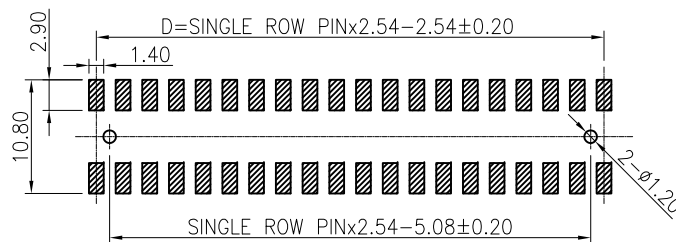
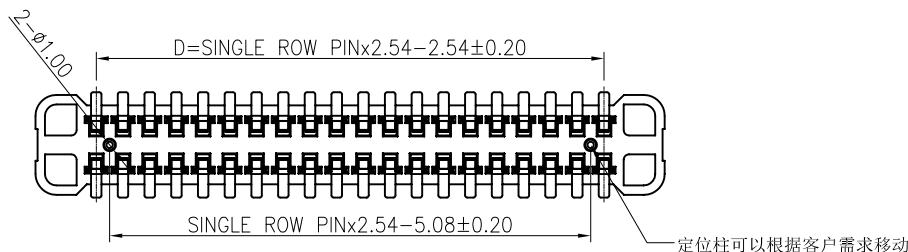
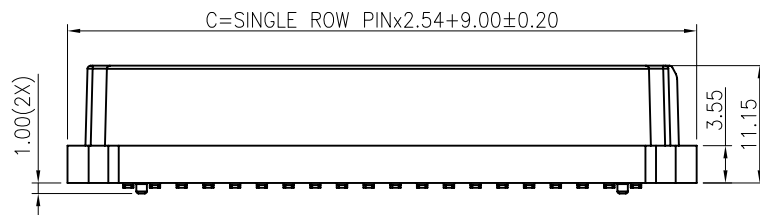
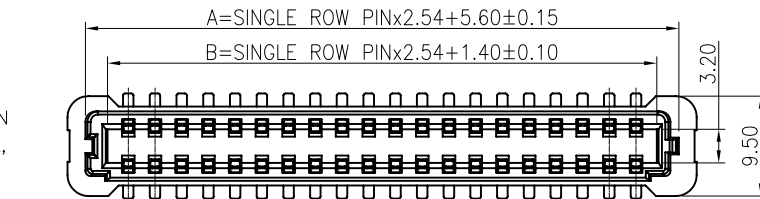
- CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST

4.Max Processing Temp:265°C Seconds 40S

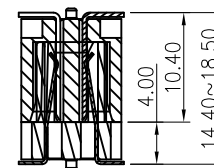
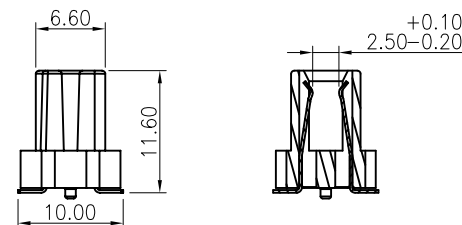
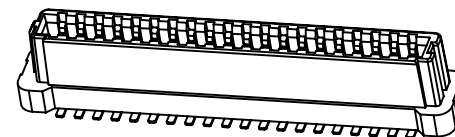
5.ORDER INFORMATION:

66H3-F XXX S1 116 R 01

Pin数码 SEE TABLE 006=2*03PIN ~ 100=2*50PIN (偶数PIN 任意选择)	端子电镀: S1=Gold TIN S2=1u"Gold/Tin S2=3u"Gold/Tin	高度: 116=11.60mm	包装方式: R=REEL
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RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE±0.05



MATING HEIGHT

合高可以从14.50-44.00mm要求定制

						OPERATION	DRAW	WLY	2023.04.27	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
						X.X ±0.40	DESIGN	Jensen	2023.04.27				
						X.XX ±0.25	CHECK	Jack	2023.04.27				
						X.XXX ±0.15	APPROVE	Andy	2023.04.27				
AO			NEW			Angle ±3°				SHEET	1/1	TITLE:	66H3 2.54mm BTB 母座直立式 SMT H=11.60mm
REV	DATE		MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1121

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP BLACK,UL94 V-0
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 3.0 AMP,AC/DC
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V,AC/Minute
- 2.3 CONTACT RESISTANCE: 100mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000 mΩ Min
- 2.5 Operation Temperature:-40°C to +125°C

3.SALT SPRAY TEST:

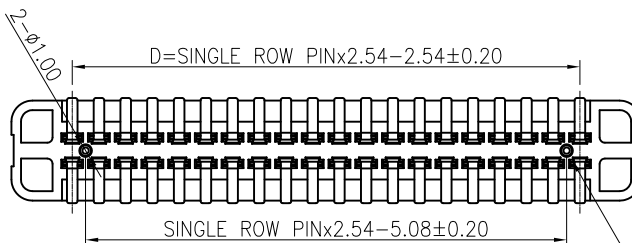
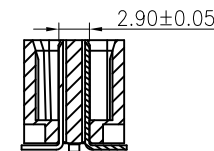
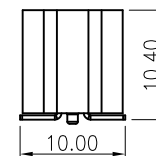
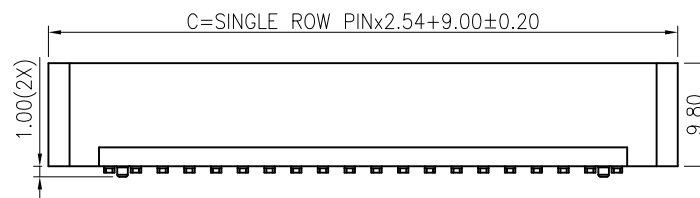
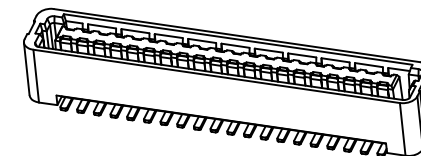
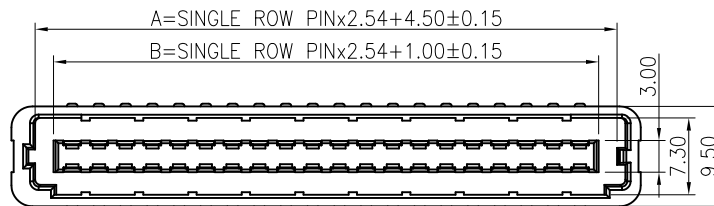
- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST

4.Max Processing Temp:265°C Seconds 40S

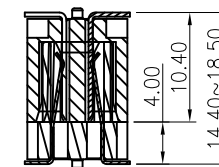
5.ORDER INFORMATION:

66H3-M XXX S1 104 R 01

Pin 数码 端子电镀: 高度: 包装方式:
SEE TABLE SN=Gold TIN 104=10.40mm R=REEL
006=2*03PIN S1=1u"Gold/Tin
~ S2=3u"Gold/Tin
100=2*50PIN
(偶数PIN 任意选择)

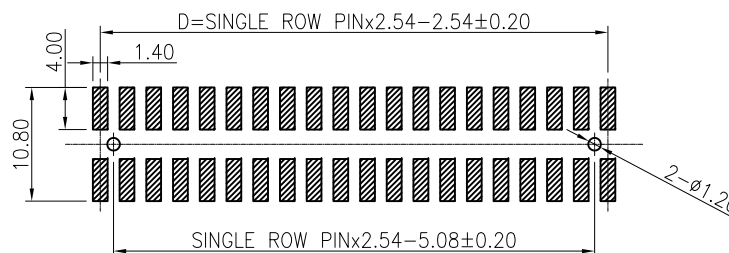


定位柱可以根据客户需求移动



MATING HEIGHT

合高可以从14.50-44.00mm要求定制



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE±0.05

						OPERATION	DRAW	Mr.Zeng	2023.04.27	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
						X.X ±0.40	DESIGN	Jensen	2023.04.27				
						X.XX ±0.25	CHECK	Jack	2023.04.27				
						X.XXX ±0.15	APPROVE	Andy	2023.04.27				
AO			NEW			Angle ±3°				SHEET	1/1	TITLE:	66H3 2.54mm BTB 公头直立式 SMT H10.40mm
REV	DATE		MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1120